

# Growth Mechanism and Kinetics of Nb<sub>3</sub>Sn in Vapor Diffusion Process

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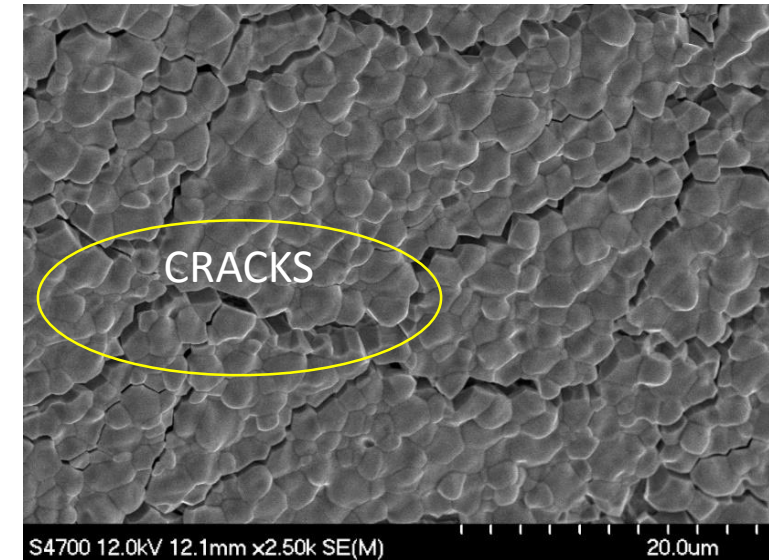
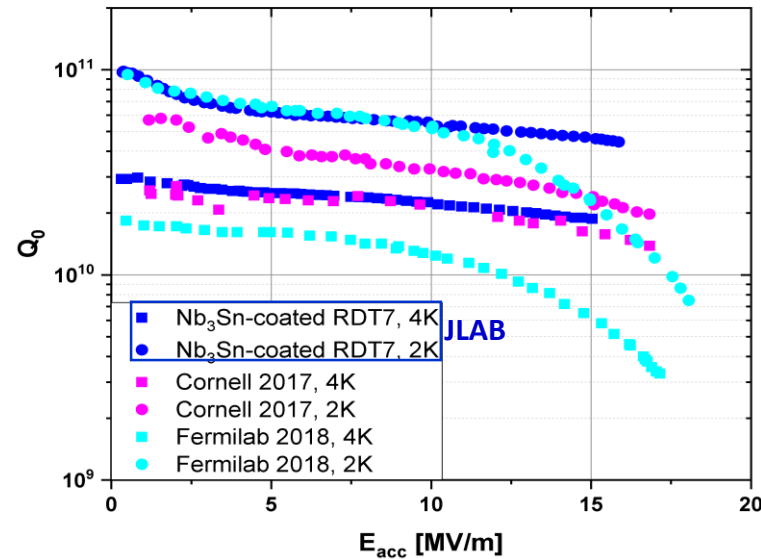
# Outline

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- Nb<sub>3</sub>Sn
- Coating growth in vapor diffusion process
  - Nucleation
  - Growth kinetics
- Summary

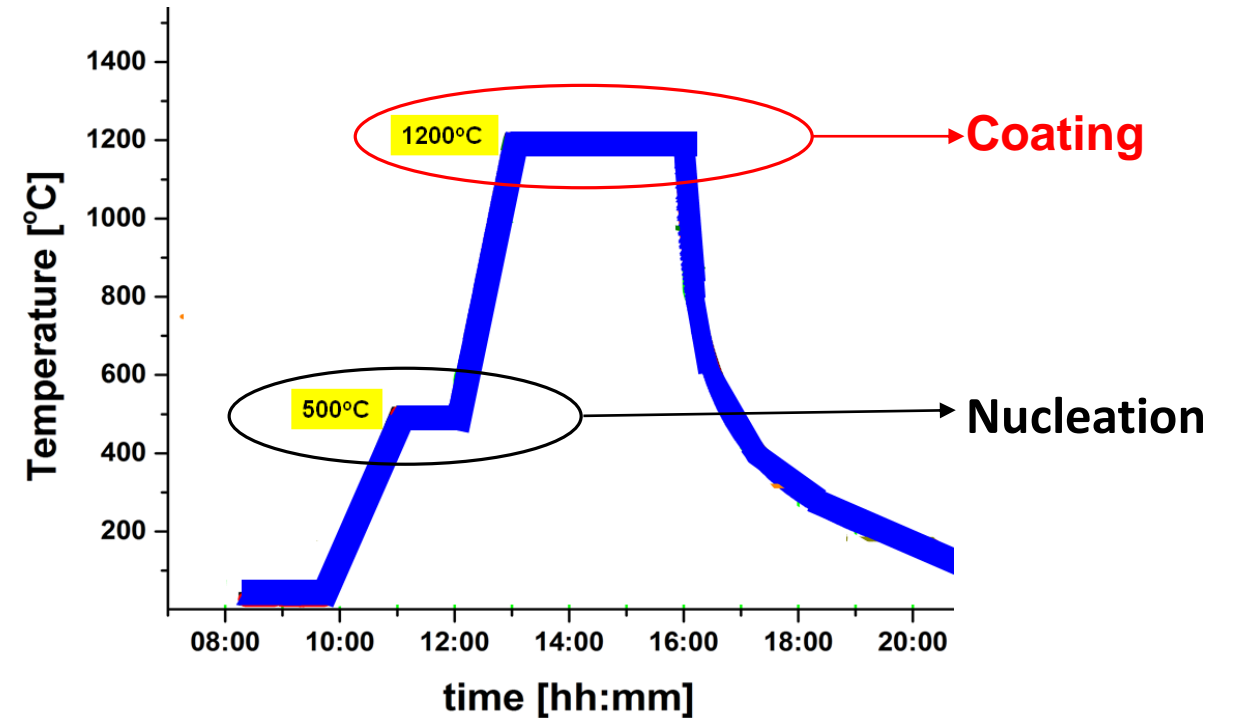
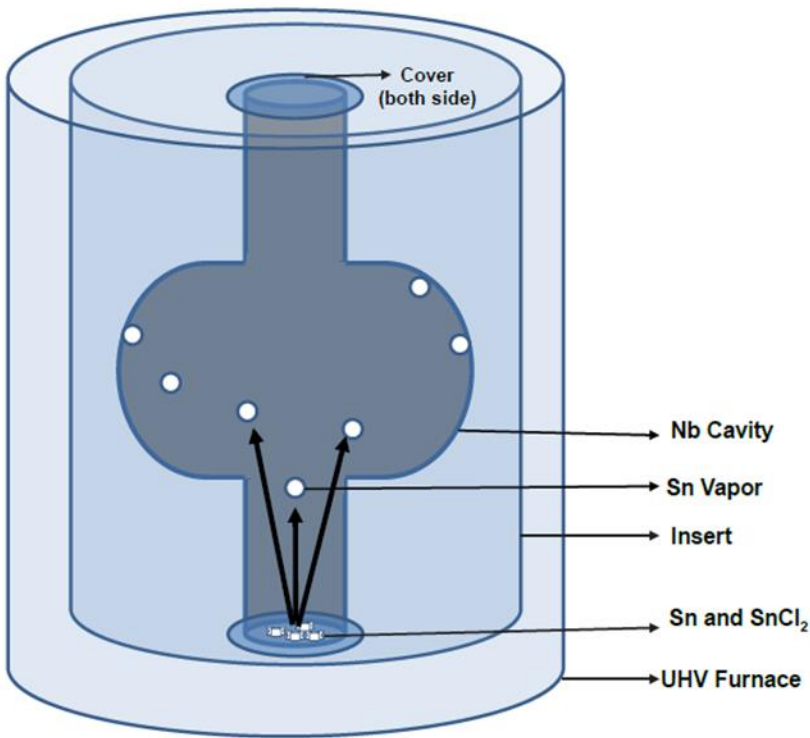
# Nb<sub>3</sub>Sn: future SRF cavity material

	Nb	Nb <sub>3</sub> Sn
T <sub>c</sub> (K)	9.25	18.3
H <sub>sh</sub> (mT)	200	400
Δ (meV)	1.45	3.1
Q <sup>BCS</sup> at 2K	5×10 <sup>10</sup>	5×10 <sup>14</sup>
Q <sup>BCS</sup> at 4K	5×10 <sup>8</sup>	5×10 <sup>10</sup>
E <sub>acc</sub> (MV/m)	50	100



- + Nb cavities are approaching the intrinsic material limit for the pure material.
- + Higher T<sub>c</sub> and H<sub>sh</sub> of Nb<sub>3</sub>Sn promise **better RF performance** (Q<sub>0</sub> and E<sub>acc</sub>) and/or **higher operating temperature** (2 K Vs 4.2 K).
- Extremely brittle material with lower thermal conductivity restricts application into a thin film/coating form.

# Vapor diffusion process

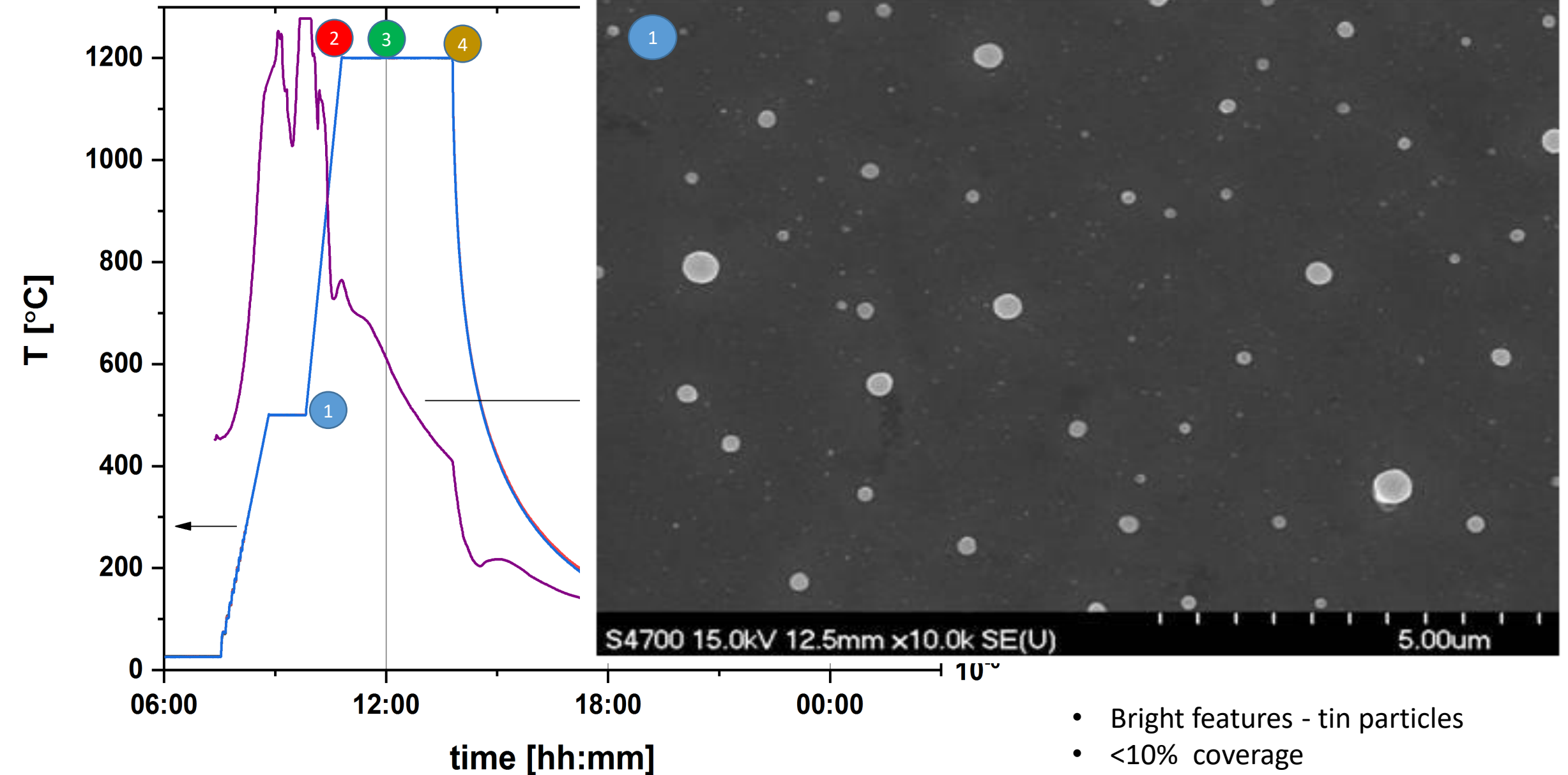


## Some variations:

- Separate heater for tin source
- Different temperatures profile for substrate and Sn source
- Pre-anodization
- Active/passive pumping

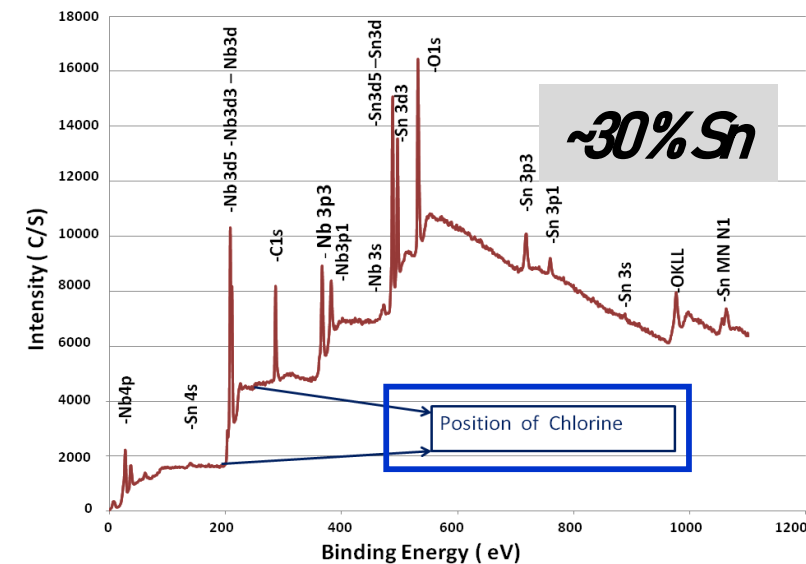
**Most successful technique so far to produce promising cavities.**

# Nb<sub>3</sub>Sn coating evolution during vapor diffusion process



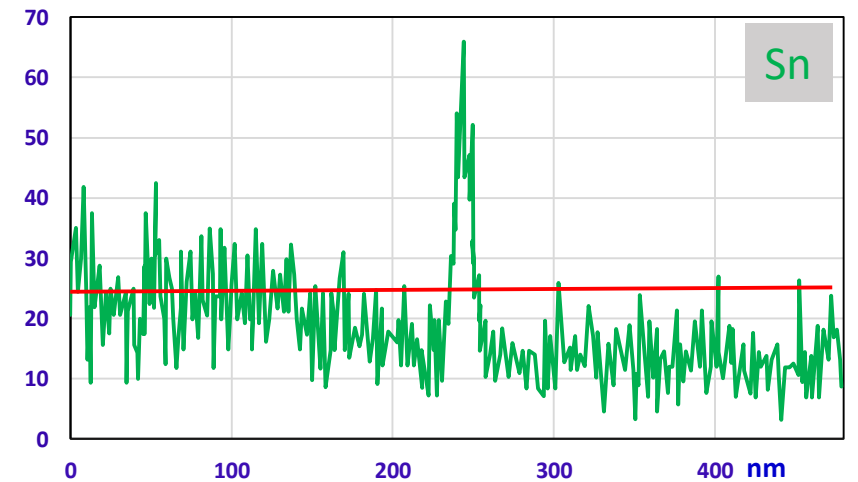
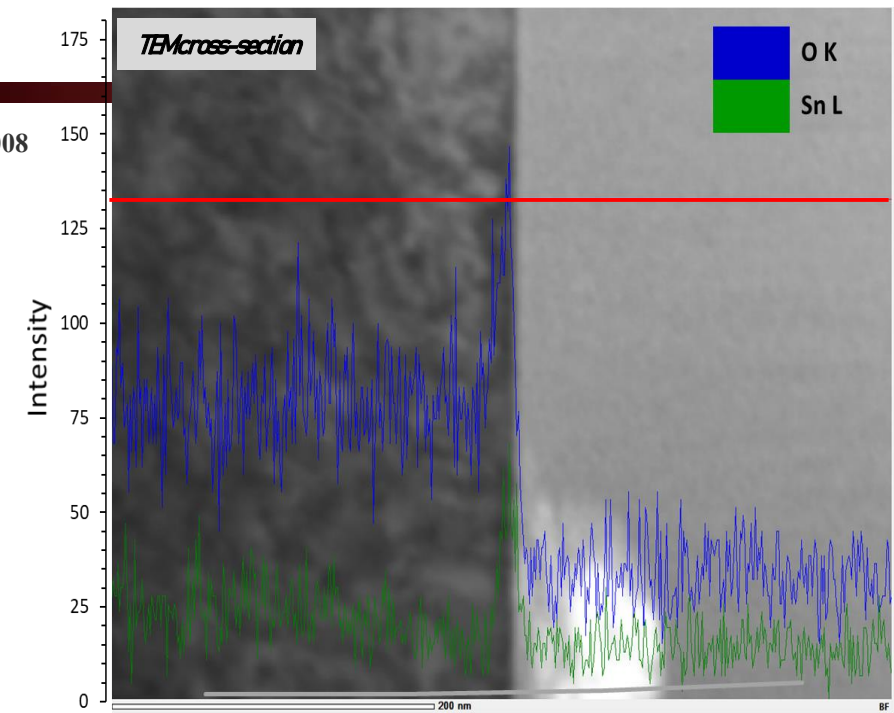
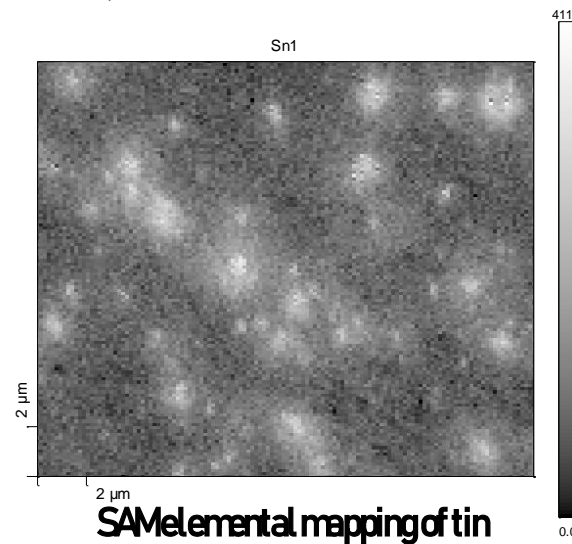
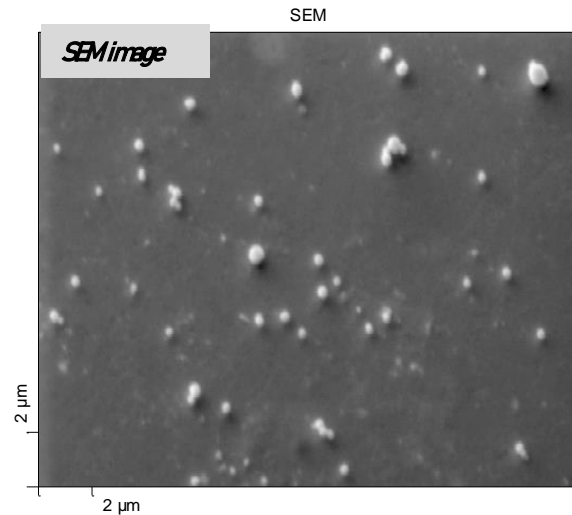
# Nucleation

Surface analysis shows  
**ultra-thin tin film** of Sn  
beside Sn particles.



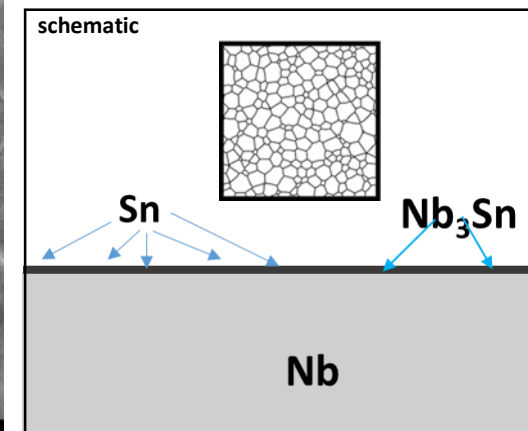
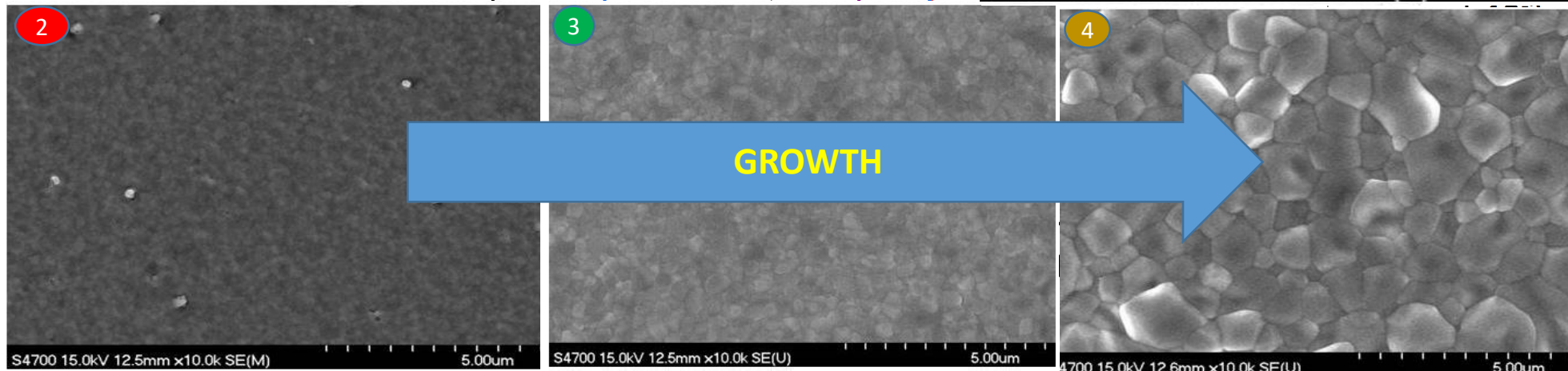
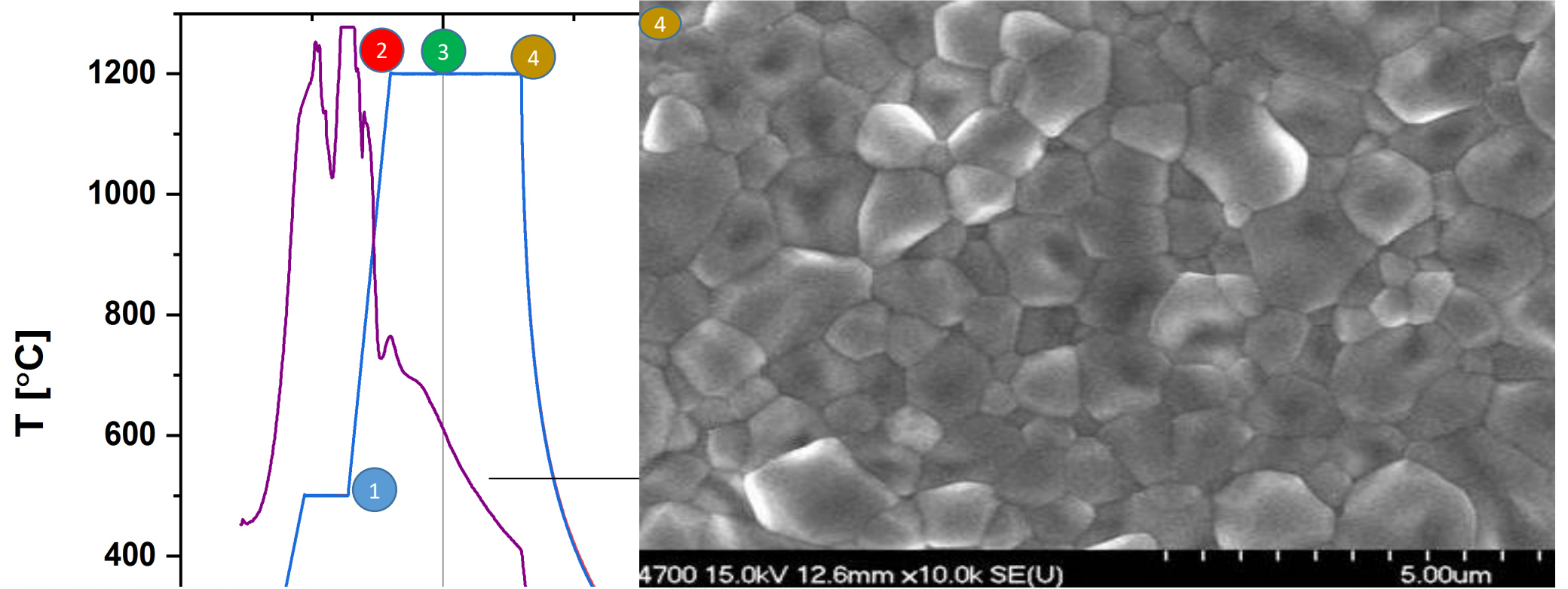
- Significantly lower amount of  $\text{SnCl}_2$  also produces similar surface with smaller tin particles.
- Advantageous to have uniform coating.

U. Pudasaini *et al* 2019 *Supercond. Sci. Technol.* 32 045008



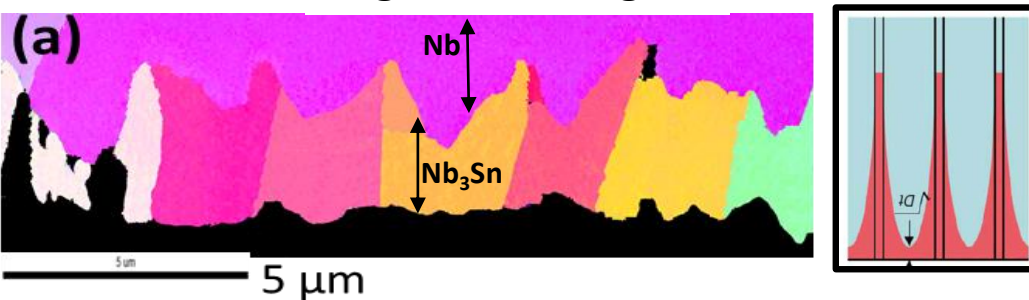
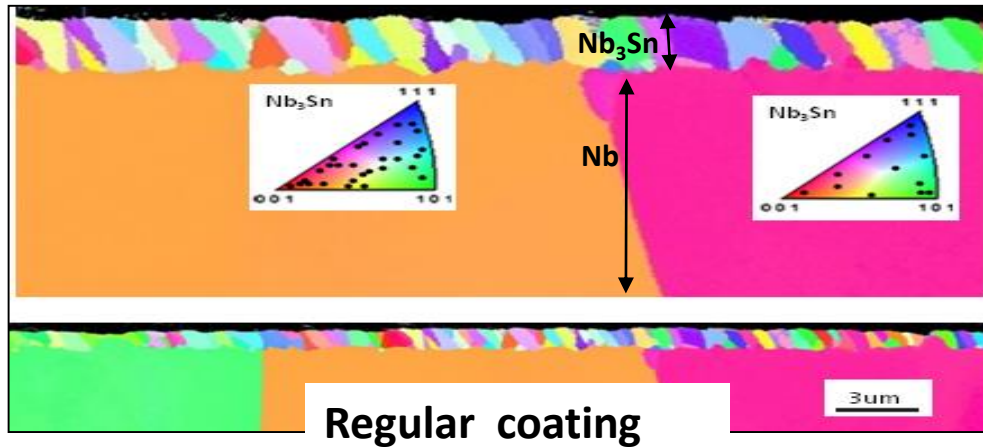


# $\text{Nb}_3\text{Sn}$ coating evolution during vapor diffusion process

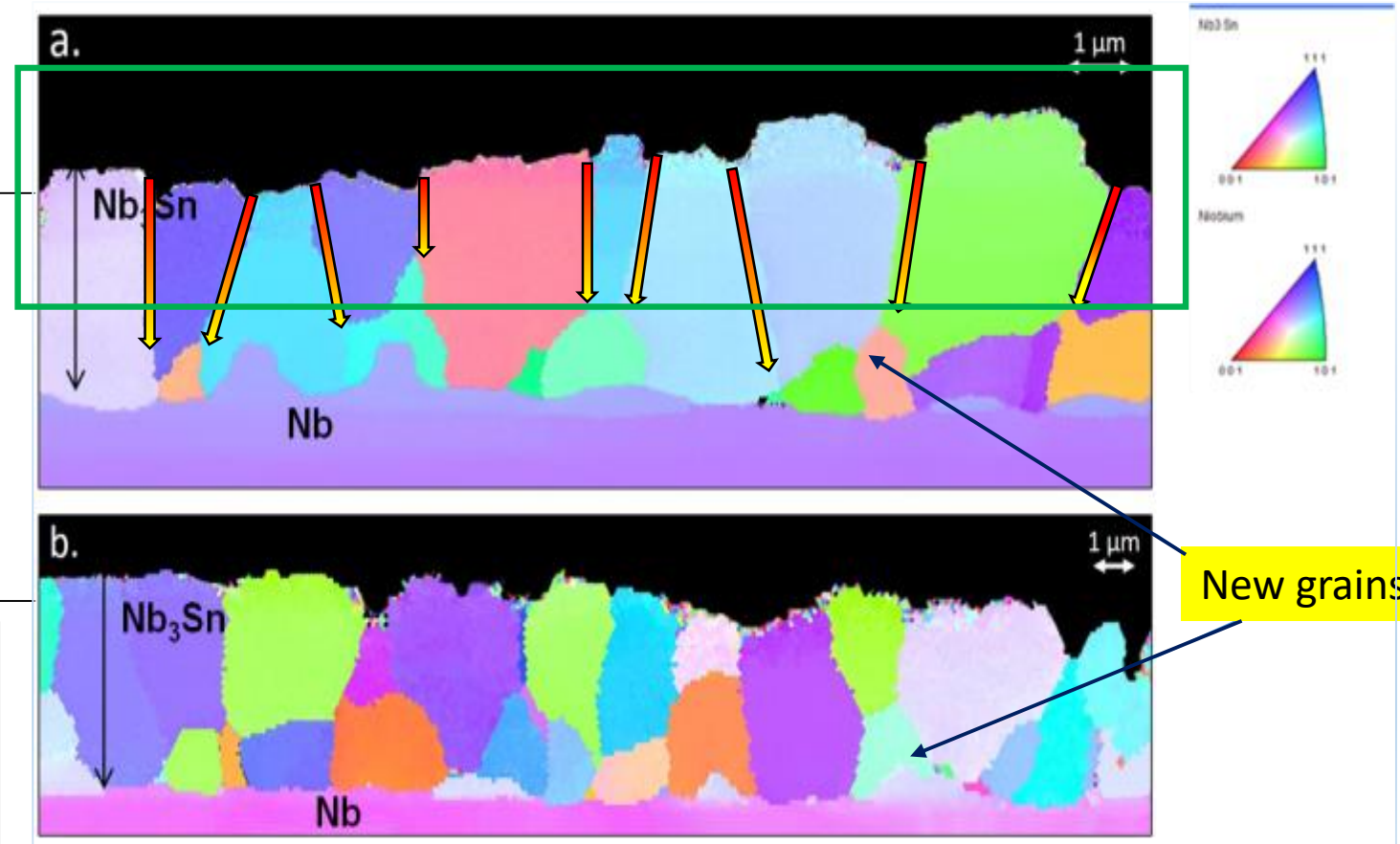


# Overcoat experiment: grain boundary diffusion

- Grain boundary diffusion is the primary mode of tin transportation.
- Additional coating forms at the interface.



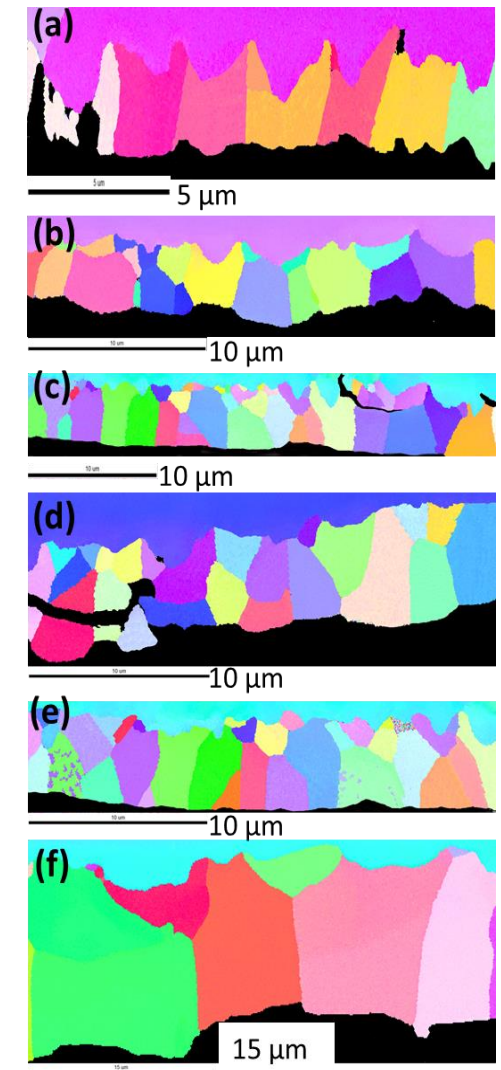
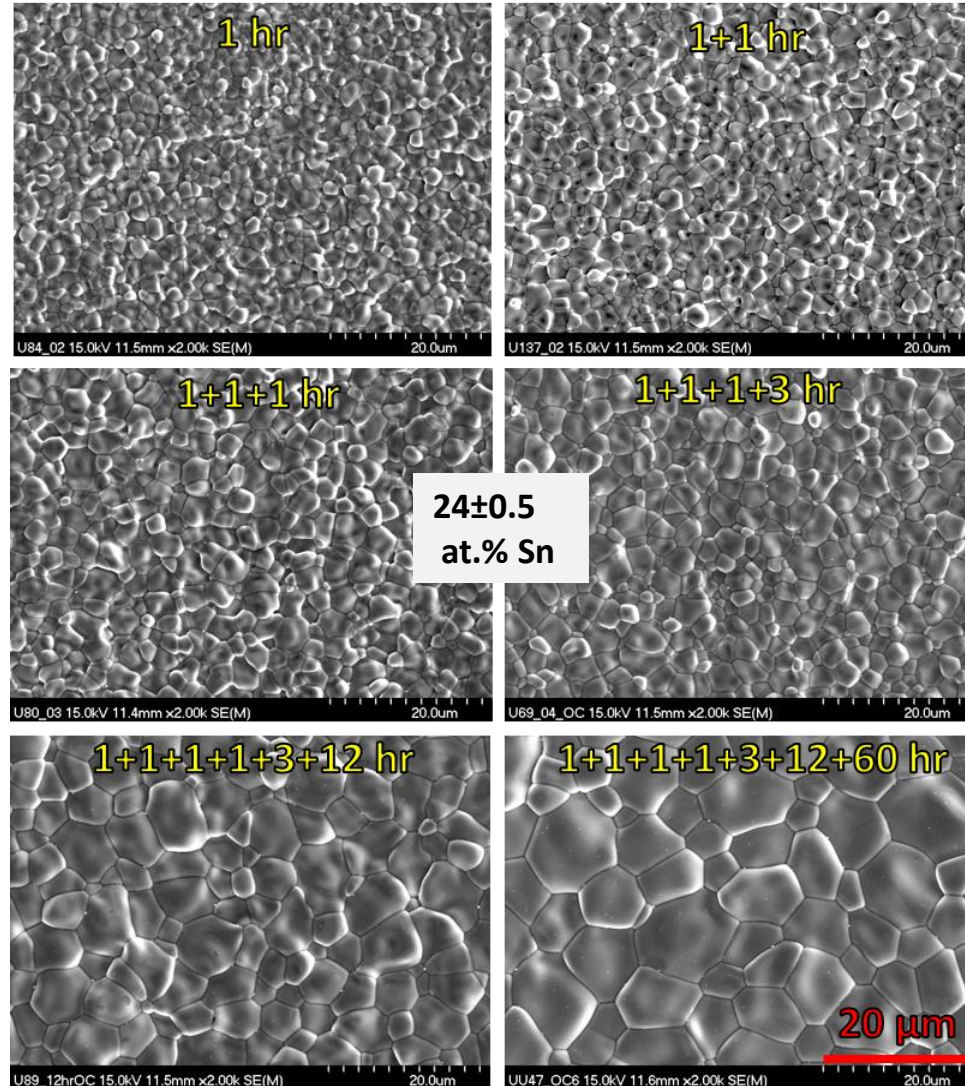
Overcoat



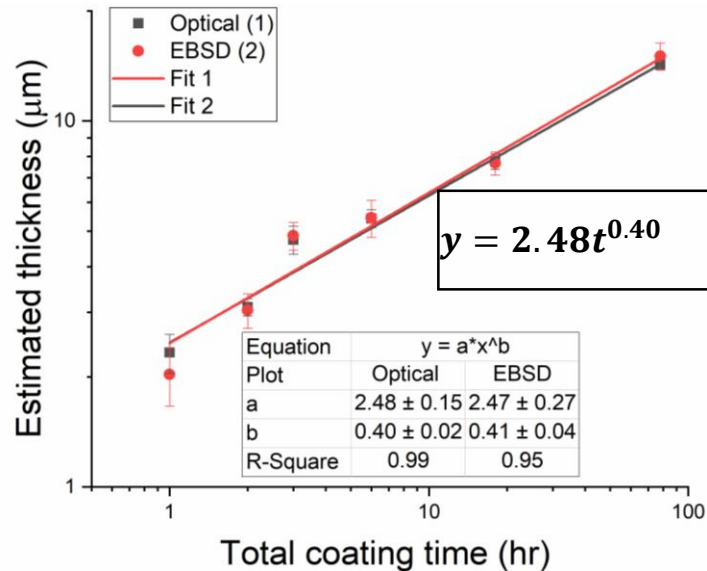


# Sequential overcoat experiments

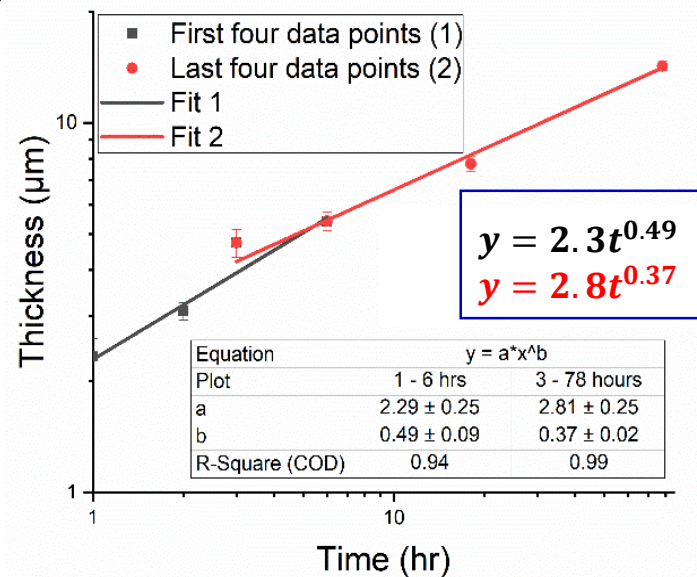
Experiment	Coating time (hr)	Total coating time (hr)
Single coat	1	1
1 <sup>st</sup> overcoat	1	2
2 <sup>nd</sup> overcoat	1	3
3 <sup>rd</sup> overcoat	3	6
4 <sup>th</sup> overcoat	12	18
5 <sup>th</sup> overcoat	60	78



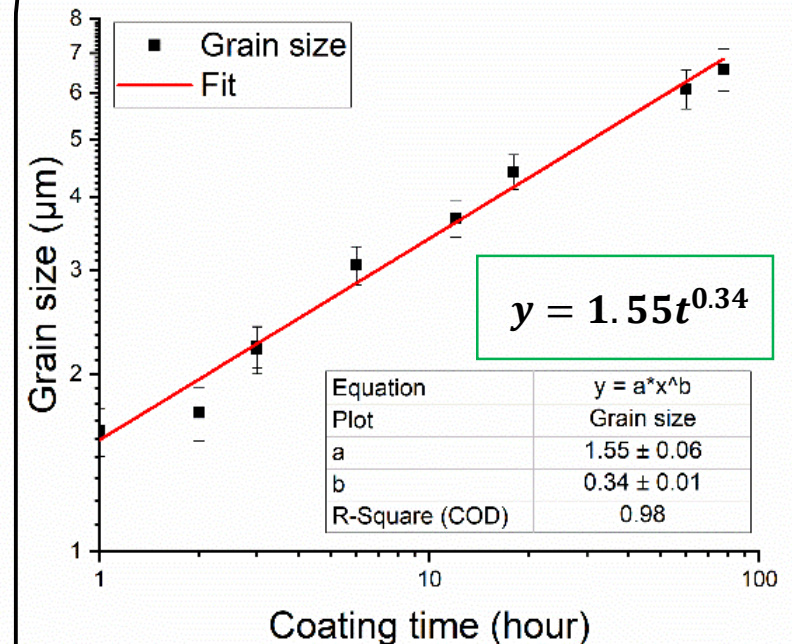
# Growth kinetics



- Follows power law: non parabolic growth
- Diffusion controlled??



- Faster growth at the beginning, slows down with longer coating

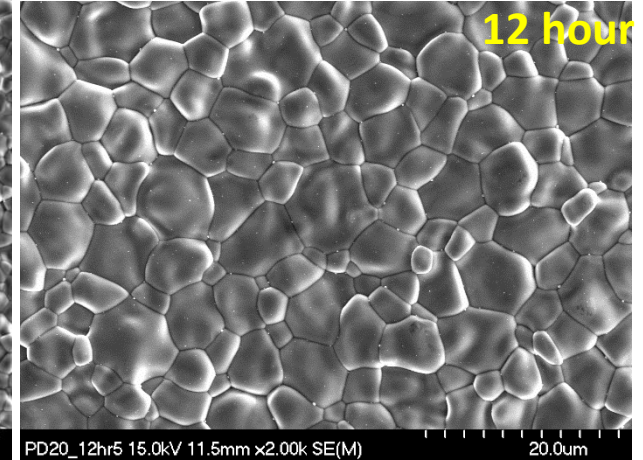
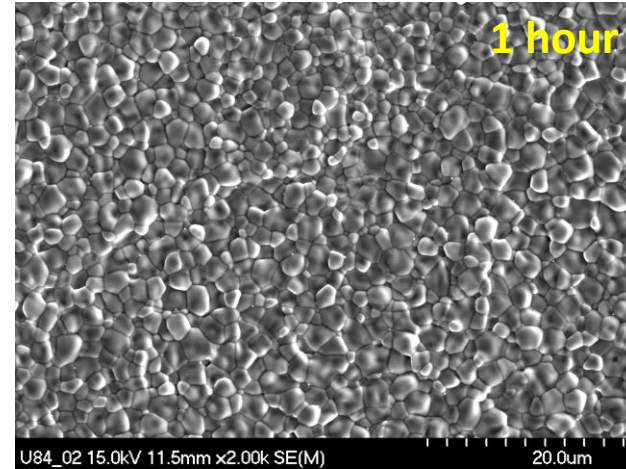


- Grain size follows power law



# Coating thickness, grain boundary diffusion and grain growth

- Bulk diffusion or fixed array of GB diffusion – should show parabolic law ( $y^2 \propto t$ ).
- Why coating thickness does not follow parabolic relation with time?



- Substantial increase in grain size: reduced number of diffusion paths
- Reduced number of diffusion path: depletion of Sn supply at the growth interface – reduction in growth rate.
- Longer diffusion path following increased thickness of the coating

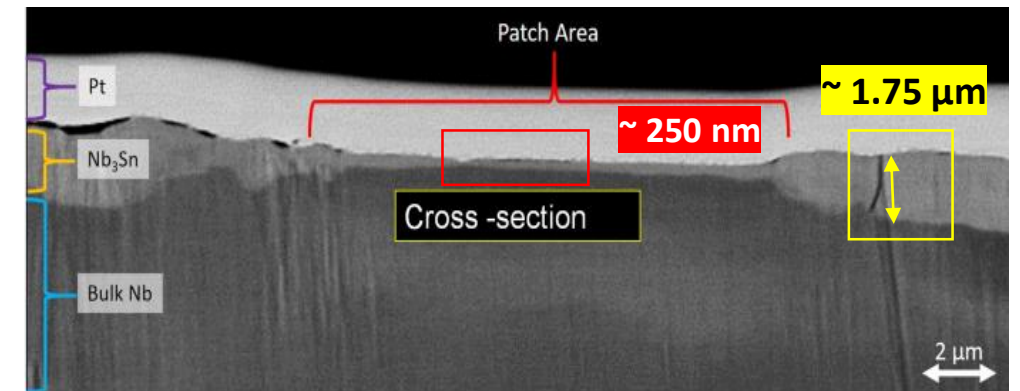
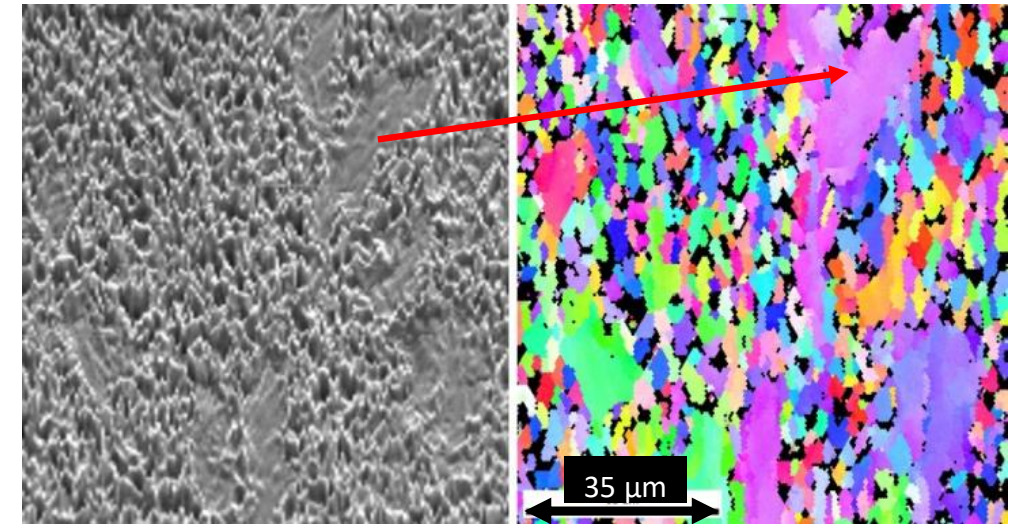
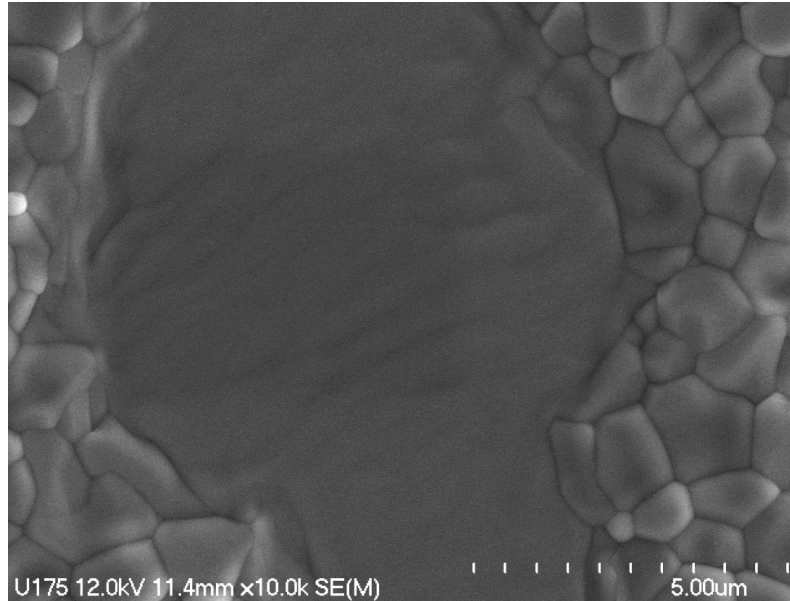
$$z = \beta(T) t^{0.5(1-m)}$$

Thickness growth exponent  $\rightarrow$   $0.5(1-m)$  Grain growth exponent  $\rightarrow$   $m$

H. H. Farrell, G. H. Gilmer and M. Suenaga,  
*J. Appl. Phys.*, vol. 45, (9), pp. 4025-4035, 1974.

# Patchy region

- Consistently reported by several labs
- EDS: Low tin concentration compared to normal coating
- Size: as small as 5  $\mu\text{m}$  to as large as 100  $\mu\text{m}$
- Cross-section: relatively thin layer
- Potentially affects RF performance



**Patchy region has only a few grain boundaries at perimeter for downward diffusion of tin resulting in slowdown of grain growth.**



# Summary

- **Two-step vapor diffusion** is the technique of choice, producing promising Nb<sub>3</sub>Sn cavities.
- 3D Tin particle and 2D tin film formation during the nucleation step of the coating is **advantageous** to have the uniform coating.
- Following nucleation, tin evaporates from tin source to form Nb<sub>3</sub>Sn layer at the niobium surface. **Grain boundary diffusion of tin** to the **Nb-Nb<sub>3</sub>Sn interface** defines further growth of the coating.
- **Non-parabolic** relationship between coating thickness and time ( $y^2 \propto t$ ) is explained by **significant grain growth**.
- Low density of grain boundaries results in thin coating in patchy regions.

# Acknowledgements

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A grayscale microscopic image showing a cluster of cells with irregular, rounded shapes and distinct cell boundaries. The cells are arranged in a honeycomb-like pattern.

**Thank you for your attention!**